

# PFU65R540G / PFD65R540G

## N-Channel Super Junction MOSFET

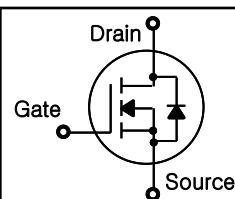
### FEATURES

- ☐ New technology for high voltage device
- ☐ Low  $R_{DS(on)}$  low conduction losses
- ☐ Small package
- ☐ Ultra low gate charge cause lower driving requirement
- ☐ 100% avalanche tested
- ☐ Halogen Free

$BV_{DSS} = 650\text{ V}$

$R_{DS(on)} = 0.48\ \Omega$

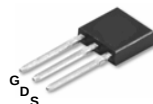
$I_D = 8.0\text{ A}$



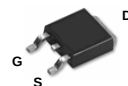
### APPLICATION

- ☐ Power Factor Correction(PFC)
- ☐ Switch mode power supply (SMPS)
- ☐ Uninterruptible Power Supply (UPS)

I-PAK(TO-251)



D-PAK(TO-252)



### Absolute Maximum Ratings $T_c = 25^\circ\text{C}$ unless otherwise specified

| Symbol          | Parameter                                                | Value       | Units               |
|-----------------|----------------------------------------------------------|-------------|---------------------|
| $V_{DS}$        | Drain-Source Voltage ( $V_{GS}=0\text{V}$ )              | 650         | V                   |
| $I_D$           | Drain Current – Continuous ( $T_c = 25^\circ\text{C}$ )  | 8.0         | A                   |
|                 | Drain Current – Continuous ( $T_c = 100^\circ\text{C}$ ) | 5.2         | A                   |
| $I_{DM(pulse)}$ | Drain Current – Pulsed * Note 1                          | 24          | A                   |
| $V_{GS}$        | Gate-Source Voltage ( $V_{DS}=0\text{V}$ )               | $\pm 30$    | V                   |
| $E_{AS}$        | Single Pulsed Avalanche Energy * Note 2                  | 185         | mJ                  |
| $I_{AR}$        | Avalanche Current * Note 1                               | 4.0         | A                   |
| $E_{AR}$        | Repetitive Avalanche Energy * Note 1                     | 0.4         | mJ                  |
| dv/dt           | Drain Source Voltage Slope, $V_{DS} \leq 480\text{V}$    | 50          | V/ns                |
|                 | Reverse Diode dv/dt, $V_{DS} \leq 480\text{V}$           | 15          | V/ns                |
| $P_D$           | Maximum Power Dissipation ( $T_c = 25^\circ\text{C}$ )   | 80          | W                   |
|                 | Derate above $25^\circ\text{C}$                          | 0.64        | W/ $^\circ\text{C}$ |
| $T_J, T_{STG}$  | Operating and Storage Temperature Range                  | -55 to +150 | $^\circ\text{C}$    |

\* Limited by maximum junction temperature

### Thermal Resistance Characteristics

| Symbol          | Parameter                     | Value | Units              |
|-----------------|-------------------------------|-------|--------------------|
| $R_{\theta JC}$ | Junction-to-Case (Maximum)    | 1.56  | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Junction-to-Ambient (Maximum) | 62    |                    |

**Electrical Characteristics**  $T_A=25\text{ }^{\circ}\text{C}$  unless otherwise specified

| Symbol                                                 | Parameter                                     | Test Conditions                                                                               | Min | Typ  | Max  | Units |
|--------------------------------------------------------|-----------------------------------------------|-----------------------------------------------------------------------------------------------|-----|------|------|-------|
| On Characteristics                                     |                                               |                                                                                               |     |      |      |       |
| V <sub>GS(th)</sub>                                    | Gate Threshold Voltage                        | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 uA                                   | 2.5 | 3.0  | 3.5  | V     |
| R <sub>DS(ON)</sub>                                    | Static Drain-Source On-Resistance             | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.0 A                                                | --  | 480  | 540  | m.ohm |
| Off Characteristics                                    |                                               |                                                                                               |     |      |      |       |
| BV <sub>DSS</sub>                                      | Drain-Source Breakdown Voltage                | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 uA                                                | 650 | --   | --   | V     |
| I <sub>DSS</sub>                                       | Zero Gate Voltage Drain Current               | V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V                                                | --  | --   | 1    | uA    |
|                                                        |                                               | V <sub>DS</sub> = 650 V, T <sub>C</sub> =125 °C                                               | --  | --   | 100  | uA    |
| I <sub>GSSF</sub>                                      | Gate-Body Leakage Current, Forward            | V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V                                                 | --  | --   | 100  | nA    |
| I <sub>GSSR</sub>                                      | Gate-Body Leakage Current, Reverse            | V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V                                                | --  | --   | -100 | nA    |
| Dynamic Characteristics                                |                                               |                                                                                               |     |      |      |       |
| g <sub>FS</sub>                                        | Forward Transconductance                      | V <sub>DS</sub> = 20V, I <sub>D</sub> = 4.0A                                                  | --  | 5.5  | --   | S     |
| R <sub>G</sub>                                         | Intrinsic Gate Resistance                     | f = 1.0 MHz, open drain                                                                       | --  | 2    | --   | ohm   |
| C <sub>iss</sub>                                       | Input Capacitance                             | V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz                                    | --  | 680  | --   | pF    |
| C <sub>oss</sub>                                       | Output Capacitance                            |                                                                                               | --  | 58   | --   | pF    |
| C <sub>rss</sub>                                       | Reverse Transfer Capacitance                  |                                                                                               | --  | 4    | --   | pF    |
| Q <sub>g</sub>                                         | Total Gate Charge                             | V <sub>DS</sub> = 480 V, I <sub>D</sub> = 8.0 A, V <sub>GS</sub> = 10 V                       | --  | 14.5 | 22   | nC    |
| Q <sub>gs</sub>                                        | Gate-Source Charge                            |                                                                                               | --  | 2.8  | --   | nC    |
| Q <sub>gd</sub>                                        | Gate-Drain Charge                             |                                                                                               | --  | 5.5  | --   | nC    |
| Switching Characteristics                              |                                               |                                                                                               |     |      |      |       |
| t <sub>d(on)</sub>                                     | Turn-On Time                                  | V <sub>DS</sub> = 380 V, I <sub>D</sub> = 4.0 A, R <sub>G</sub> = 12 Ω, V <sub>GS</sub> = 10V | --  | 5.5  | --   | ns    |
| t <sub>r</sub>                                         | Turn-On Rise Time                             |                                                                                               | --  | 3.5  | --   | ns    |
| t <sub>d(off)</sub>                                    | Turn-Off Delay Time                           |                                                                                               | --  | 55   | 75   | ns    |
| t <sub>f</sub>                                         | Turn-Off Fall Time                            |                                                                                               | --  | 6.5  | 10   | ns    |
| Source-Drain Diode Maximum Ratings and Characteristics |                                               |                                                                                               |     |      |      |       |
| I <sub>S</sub>                                         | Continuous Source-Drain Diode Forward Current |                                                                                               | --  | --   | 8.0  | A     |
| I <sub>SM</sub>                                        | Pulsed Source-Drain Diode Forward Current     |                                                                                               | --  | --   | 23.4 |       |
| V <sub>SD</sub>                                        | Source-Drain Diode Forward Voltage            | I <sub>S</sub> = 8.0 A, V <sub>GS</sub> = 0 V                                                 | --  | 0.9  | 1.2  | V     |
| t <sub>rr</sub>                                        | Reverse Recovery Time                         | I <sub>S</sub> = 8.0 A                                                                        | --  | 220  | --   | ns    |
| Q <sub>rr</sub>                                        | Reverse Recovery Charge                       | di/dt = 100 A/μs                                                                              | --  | 2.2  | --   | μC    |

**Notes ;**

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $V_{DD}=50\text{ V}, R_G=25\text{ }\Omega$ , Starting  $T_J=25\text{ }^{\circ}\text{C}$

# Typical Characteristics

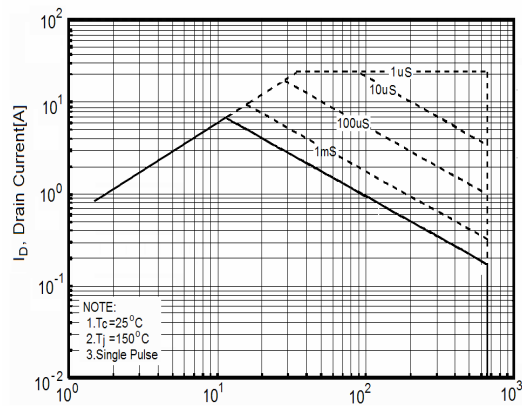


Figure 1. Safe Operating Area

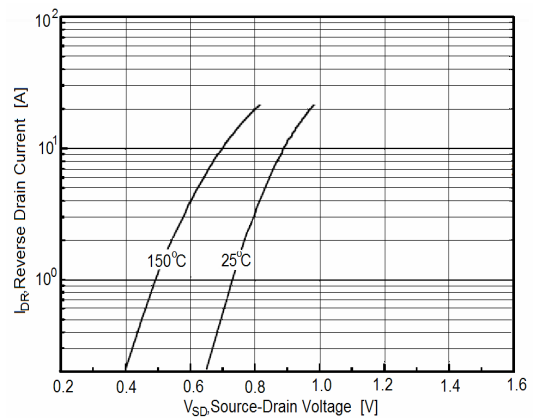


Figure 2. Source-Drain Diode Forward Voltage

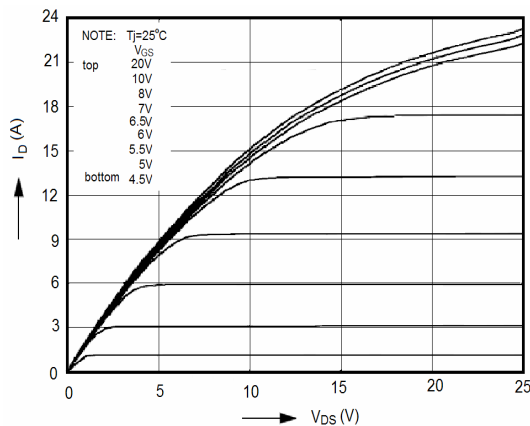


Figure 3. Output Characteristics

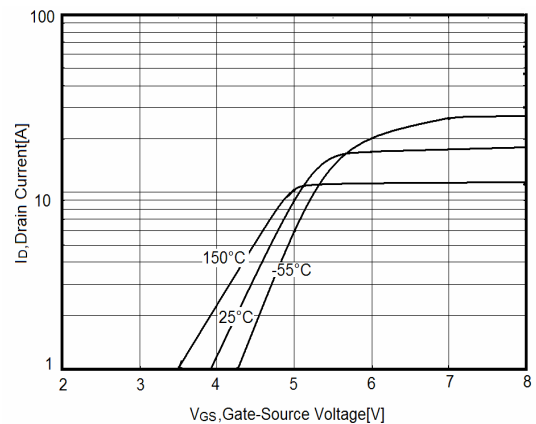


Figure 4. Transfer Characteristics

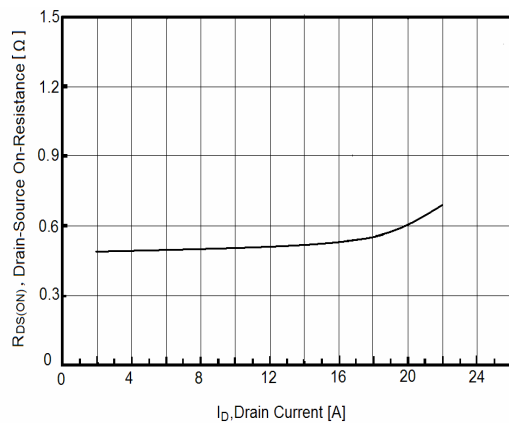


Figure 5. Static Drain-Source On Resistance

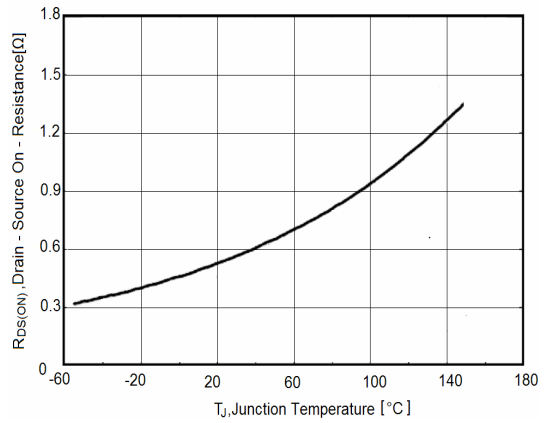


Figure 6.  $R_{DS(on)}$  vs. Junction Temperature

# Typical Characteristics (continued)

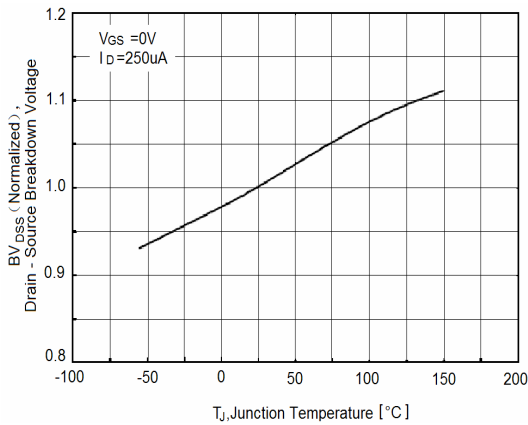


Figure 7. BVDss vs. Junction Temperature

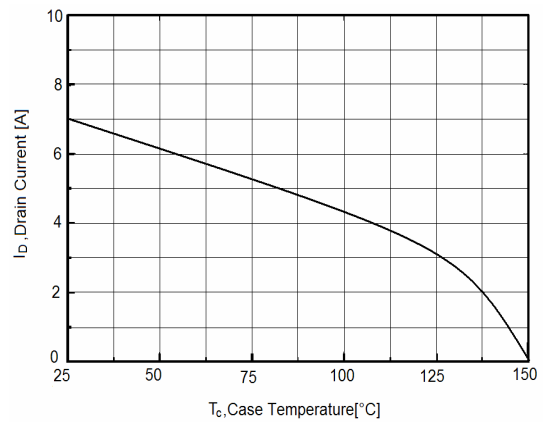


Figure 8. Maximum ID vs. Junction Temperature

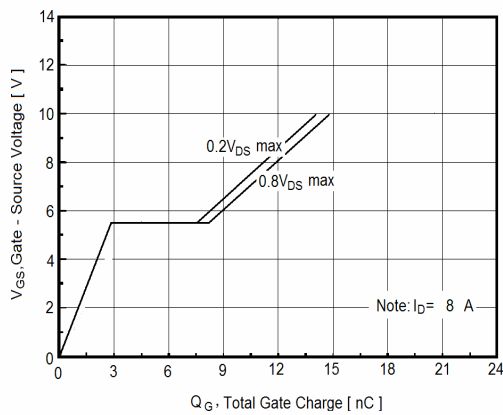


Figure 9. Gate Charge Waveforms

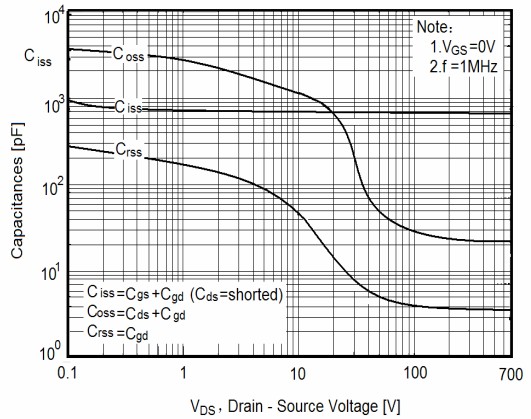


Figure 10. Capacitance

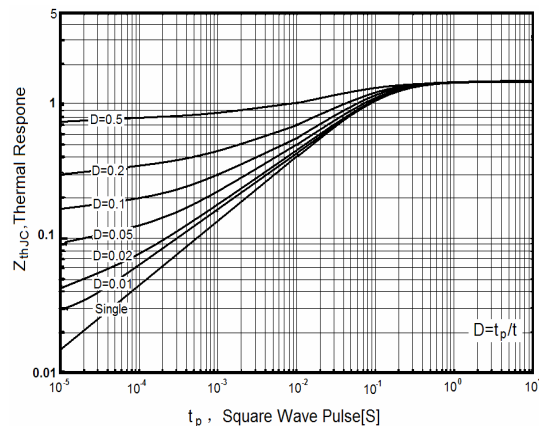
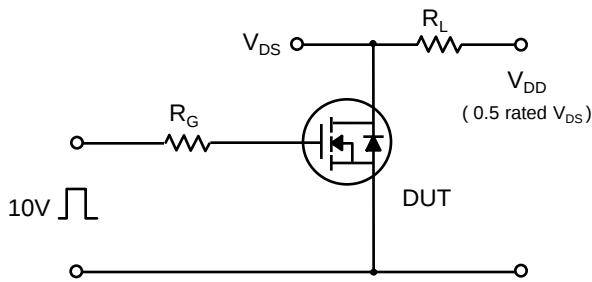
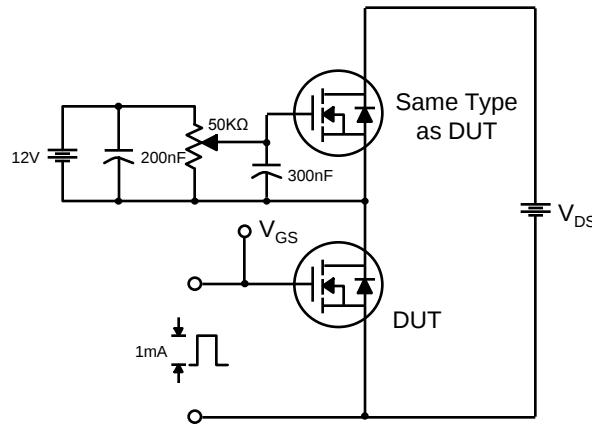


Figure 11. Transient Thermal Response Curve

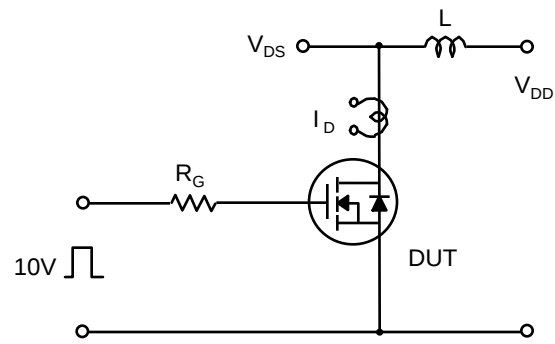
# Characteristics Test Circuit & Waveform



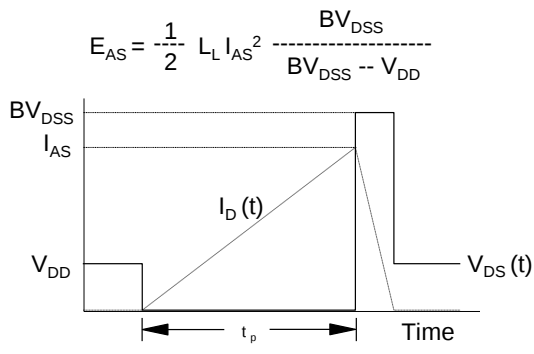
Switching Time Test Circuit & Waveforms



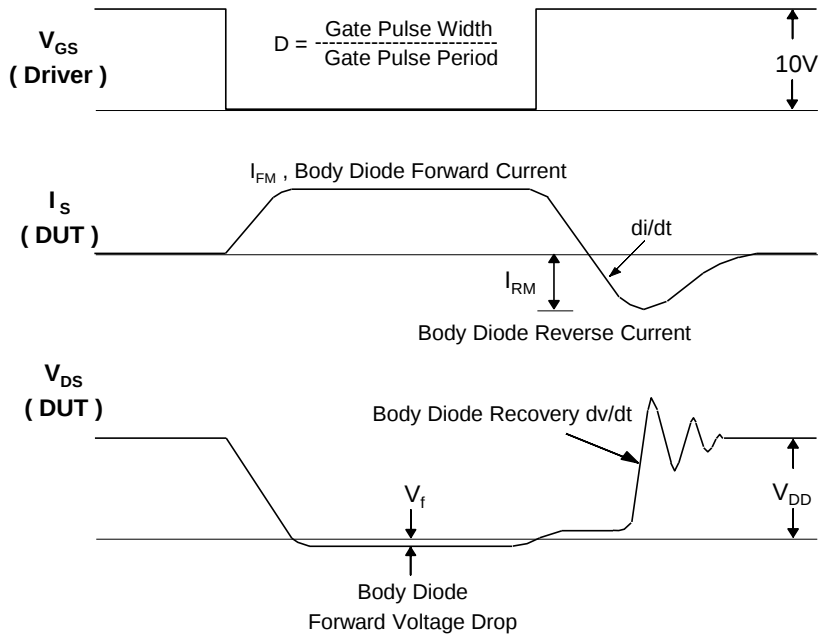
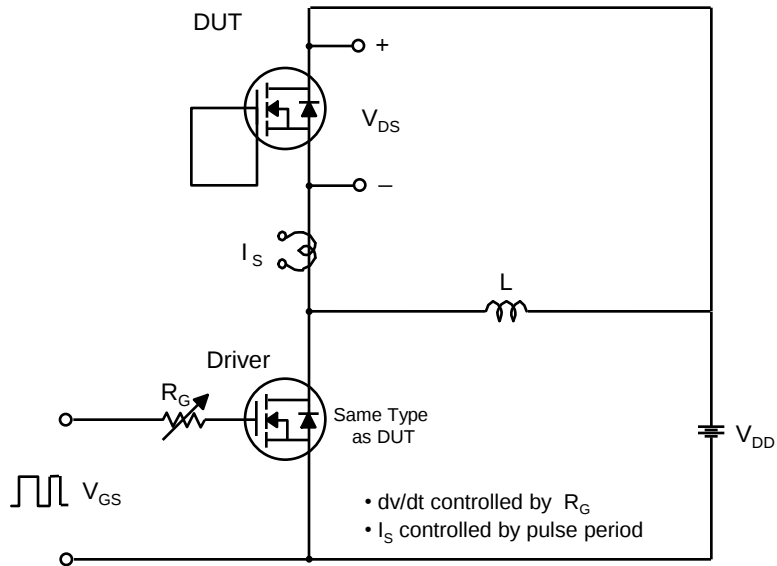
Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveforms



# Characteristics Test Circuit & Waveform (continued)



Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms